

SONY®

CXK5864CP/CM -70LL/10LL

8,192-word × 8-bit High Speed CMOS Static RAM

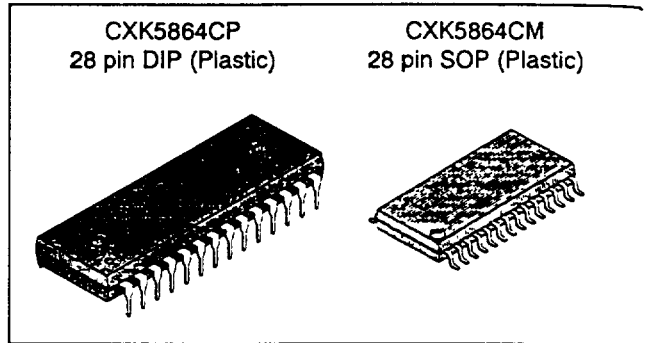
205-760

Description

CXK5864CP/CM are 65,536 bits high speed CMOS static RAMs organized as 8,192 words by 8 bits and operates from a single 5V supply. These IC are suitable for use in high speed and low power applications in which battery back up for nonvolatility is required.

Features

- Fast access time: (Access time)
 CXK5864CP/CM-70LL 70ns (Max.)
 CXK5864CP/CM-10LL 100ns (Max.)
- Low power operation:
 CXK5864CP/CM-70LL, 10LL;
 Standby/Operation: 1 μW (Typ.) /15mW (Typ.)
- Single power supply 5V: +5V ± 10%
- Fully static memory ... No clock or timing strobe required
- Equal access and cycle time
- Common data input and output: three state output
- Directly TTL compatible: All inputs and outputs
- Low voltage data retention: 2.0V (Min.)
- Available in 28 pin 600mil DIP and 450mil SOP



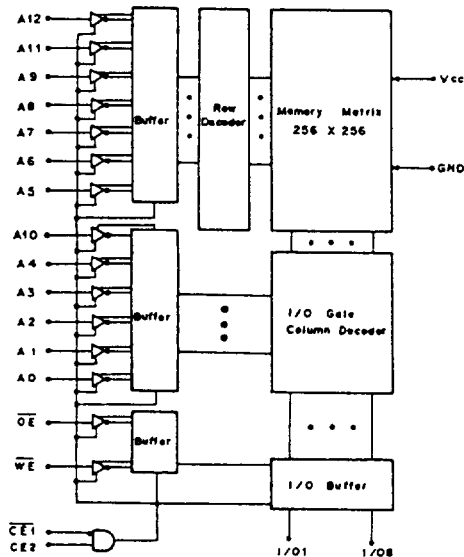
Function

8,192-word × 8-bit static RAM

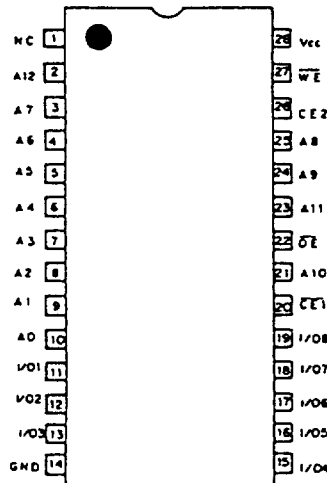
Structure

Silicon gate CMOS IC

Block Diagram



Pin Configuration (Top View)



Pin Description

Symbol	Description
A0 to A12	Address input
I/O1 to I/O8	Data input output
$\overline{CE}1, CE2$	Chip enable 1, 2 input
\overline{WE}	Write enable input
\overline{OE}	Output enable input
Vcc	+5V Power supply
GND	Ground
NC	No connection

Absolute Maximum Ratings

(Ta=25°C, GND=0V)

Item	Symbol	Rating	Unit
Supply voltage	V _{CC}	-0.5 to +7.0	V
Input voltage	V _{IN}	-0.5 * to V _{CC} +0.5	V
Input and output voltage	V _{I/O}	-0.5 * to V _{CC} +0.5	V
Allowable power dissipation	P _D	CXK5864CP	1.0
		CXK5864CM	0.7
Operating temperature	T _{opr}	0 to +70	°C
Storage temperature	T _{stg}	-55 to +150	°C
Soldering temperature • time	T _{solder}	260 • 10	°C • sec

* V_{IN}, V_{I/O}=-3.0V Min. for pulse width less than 50ns.

Truth Table

CE1	CE2	OE	WE	Mode	I/O1 to I/O8	V _{CC} Current
H	X	X	X	Not selected	High Z	I _{SB1} , I _{SB2}
X	L	X	X	Not selected	High Z	I _{SB1} , I _{SB2}
L	H	H	H	Output disable	High Z	I _{CC1} , I _{CC2}
L	H	L	H	Read	Data out	I _{CC1} , I _{CC2}
L	H	X	L	Write	Data in	I _{CC1} , I _{CC2}

X : "H" or "L"

DC Recommended Operating Conditions (Ta=0 to +70°C, GND=0V)

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	V _{CC}	4.5	5.0	5.5	V
Input high voltage	V _{IH}	2.2	—	V _{CC} +0.3	V
Input low voltage	V _{IL}	-0.3 *	—	0.8	V

* V_{IL}=-3.0V Min. for pulse width less than 50ns.

Electrical Characteristics

• DC and operating characteristics

(V_{CC}=5V ± 10%, GND=0V, T_a=0 to +70 °C)

Item	Symbol	Test conditions	- 70LL/10LL			Unit
			Min.	Typ. *	Max.	
Input leak current	I _{LI}	V _{IN} =GND to V _{CC}	-500	—	500	nA
Output leak current	I _{LO}	V _{I/O} =GND to V _{CC} CE1=V _{IH} or CE2=V _{IL} or \overline{OE} =V _{IH} or WE=V _{IL}	-500	—	500	nA
Operating supply current	I _{CC1}	CE1=V _{IL} , CE2=V _{IH} , V _{IN} =V _{IH} or V _{IL} , I _{OUT} =0mA	—	3	10	mA
Average operating current	I _{CC2}	Min. cycle Duty=100%, I _{OUT} =0mA	—	30	50	mA
Standby current	I _{SB1}	CE2 ≤ 0.2V or { CE1 ≥ V _{CC} -0.2V CE2 ≥ V _{CC} -0.2V	—	0.2	6	μA
	I _{SB2}	CE1=V _{IH} or CE2=V _{IL}	—	0.4	2	mA
Output high voltage	V _{OH}	I _{OH} =-1.0mA	2.4	—	—	V
Output low voltage	V _{OL}	I _{OL} =2.1mA	—	—	0.4	V

* V_{CC}=5V, T_a=25 °C

Pin capacitance

(T_a=25 °C, f=1MHz)

Item	Symbol	Test conditions	Min.	Max.	Unit
Input capacitance	C _{IN}	V _{IN} =0V	—	8	pF
Input/Output capacitance	C _{I/O}	V _{I/O} =0V	—	6	pF

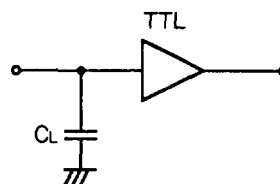
Note) This parameter is sampled and is not 100% tested.

AC characteristics

• AC test conditions (V_{CC}=5V ± 10%, T_a=0 to +70 °C)

Item	Conditions	
Input pulse high level	V _{IH} =2.2V	
Input pulse low level	V _{IL} =0.8V	
Input rise time	t _r =5ns	
Input fall time	t _f =5ns	
Input and output reference level	1.5V	
Output load conditions	10LL	C _L * =100pF, 1TTL
	70LL	C _L * =30pF, 1TTL

* C_L includes scope and jig capacitances.



• Read cycle

Item	Symbol	-70LL		-10LL		Unit
		Min.	Max.	Min.	Max.	
Read cycle time	t _{RC}	70	—	100	—	ns
Address access time	t _{AA}	—	70	—	100	ns
Chip enable access time ($\overline{CE1}$, CE2)	t _{CO1} t _{CO2}	—	70	—	100	ns
Output enable to output valid	t _{OE}	—	35	—	50	ns
Output hold from address change	t _{OH}	15	—	15	—	ns
Chip enable to output in low Z ($\overline{CE1}$, CE2)	t _{LZ1} t _{LZ2}	10	—	10	—	ns
Output enable to output in low Z (\overline{OE})	t _{OLZ}	5	—	5	—	ns
Chip disable to output in high Z ($\overline{CE1}$, CE2)	t _{HZ1} * t _{HZ2} *	0	30	0	35	ns
Output disable to output in high Z (\overline{OE})	t _{OHZ} *	0	30	0	35	ns

* t_{HZ1}, t_{HZ2} and t_{OHZ} are defined as the time at which the outputs become the high impedance state and are not referred to output voltage levels.

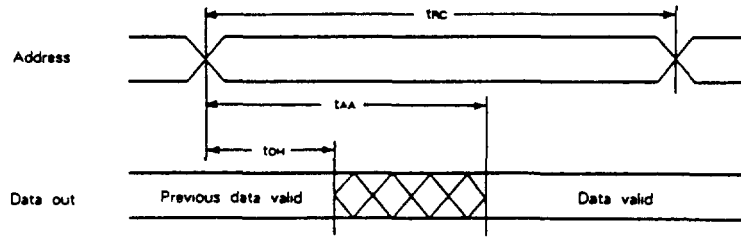
• Write cycle

Item	Symbol	-70LL		-10LL		Unit
		Min.	Max.	Min.	Max.	
Write cycle time	t _{WC}	70	—	100	—	ns
Address valid to end of write	t _{AW}	60	—	75	—	ns
Chip enable to end of write	t _{CW}	60	—	75	—	ns
Data to write time overlap	t _{DW}	30	—	35	—	ns
Data hold from write time	t _{DH}	0	—	0	—	ns
Write pulse width	t _{WP}	45	—	60	—	ns
Address setup time	t _{AS}	0	—	0	—	ns
Write recovery time (\overline{WE})	t _{WR}	0	—	0	—	ns
Write recovery time ($\overline{CE1}$, CE2)	t _{WR1}	0	—	0	—	ns
Output active from end of write	t _{OW}	10	—	10	—	ns
Write to output in high Z	t _{WHZ} *	0	30	0	35	ns

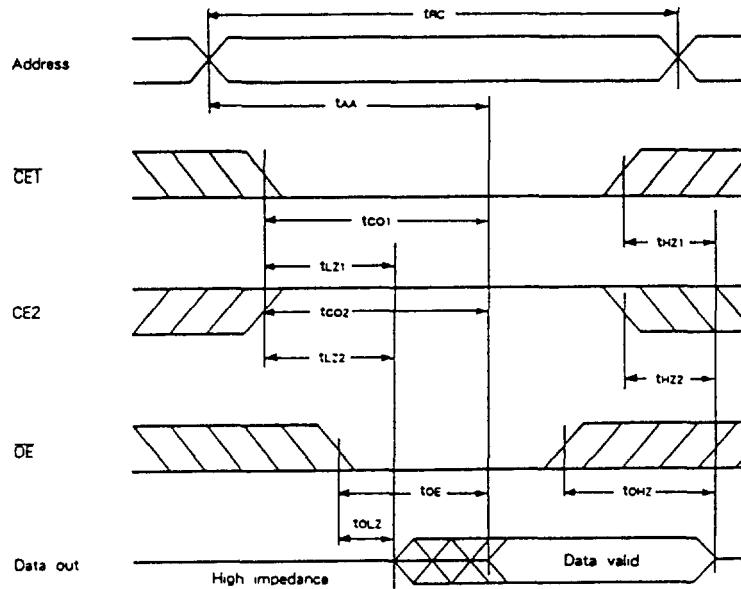
* t_{WHZ} is defined as the time at which the outputs become the high impedance state and are not referred to output voltage levels.

Timing Waveform

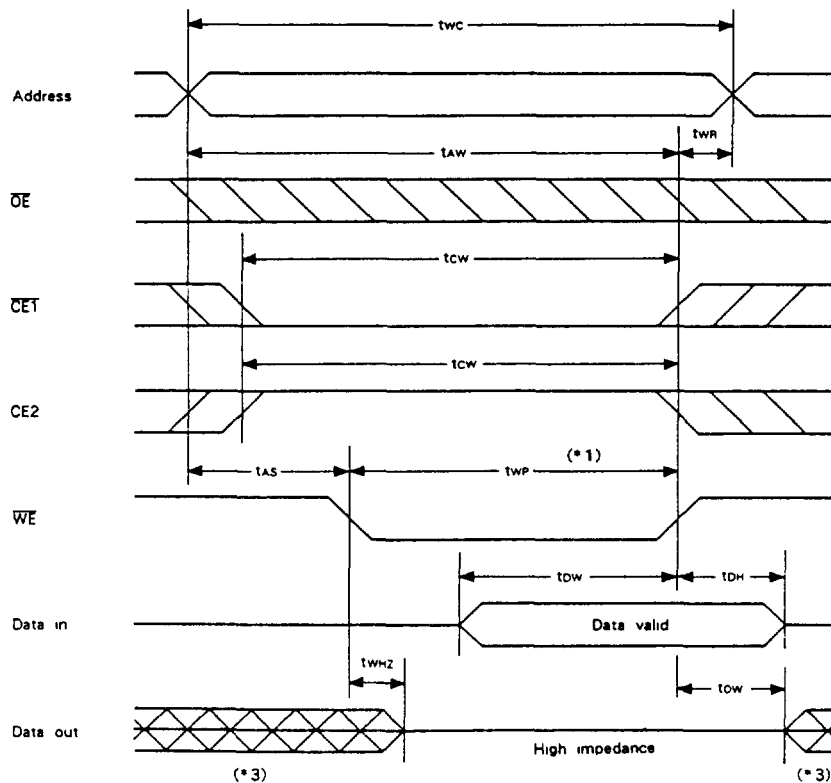
- Read cycle (1) : $\overline{CE1}=\overline{OE}=V_{IL}$, $CE2=V_{IH}$, $\overline{WE}=V_{IH}$



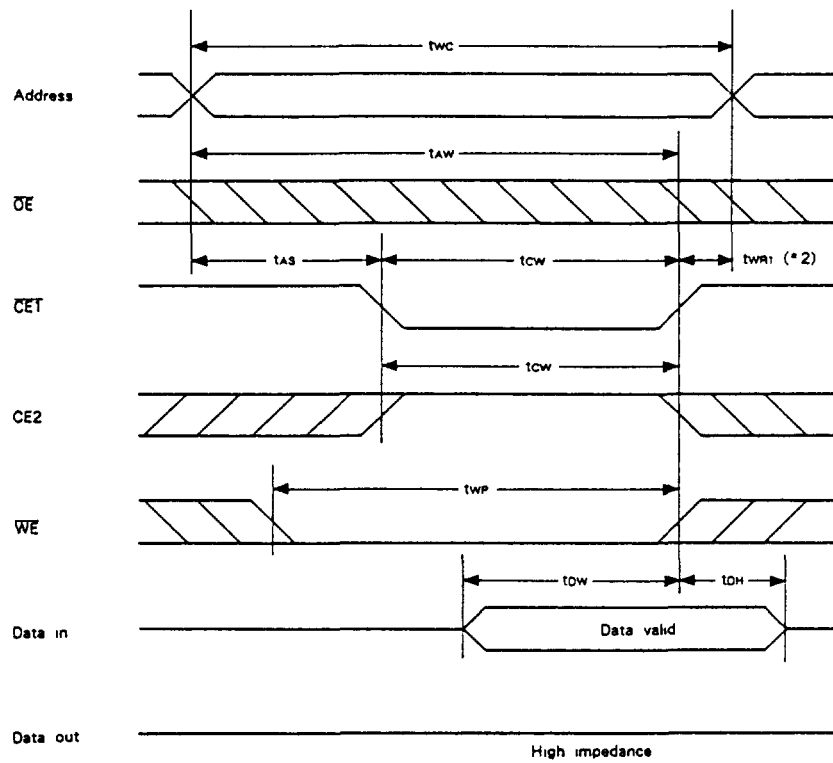
- Read cycle (2) : $\overline{WE}=V_{IH}$



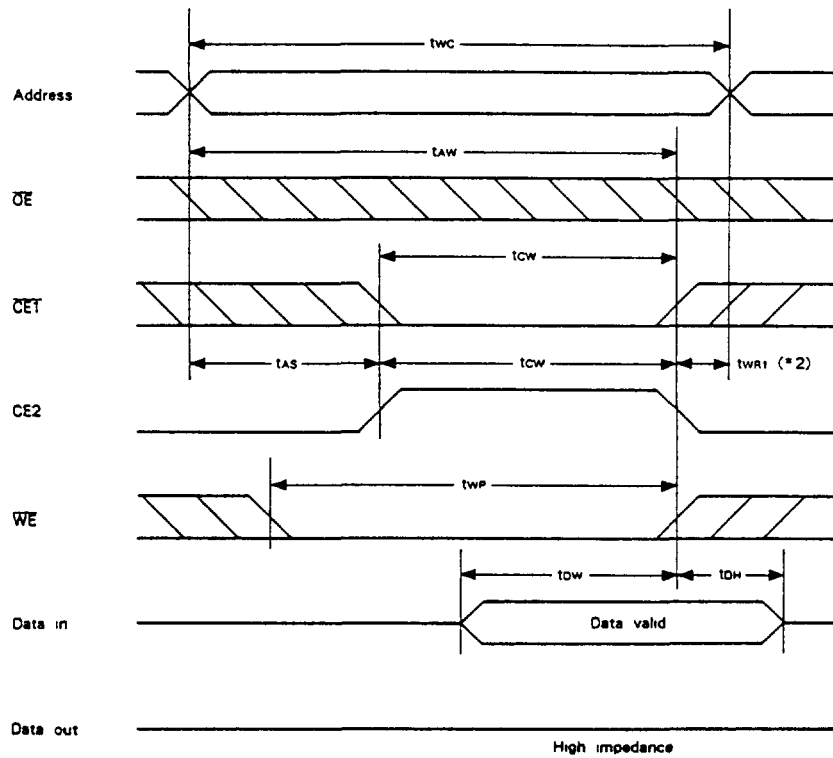
- Write cycle (1) : \overline{WE} control



• Write cycle (2) : $\overline{CE1}$ control



• Write cycle (3) : CE2 control



Note)

- * 1. Write is executed when both $\overline{CE1}$ and \overline{WE} are at low and CE2 is at high simultaneously.
- * 2. t_{WR1} is tested from either the rising edge of $\overline{CE1}$ or the falling edge of CE2, whichever comes earlier, until the end of the write cycle.
- * 3. Do not apply the data input voltage of the opposite phase to the output while the I/O pin is in output condition.

Data Retention Characteristics

(Ta=0 to +70 °C)

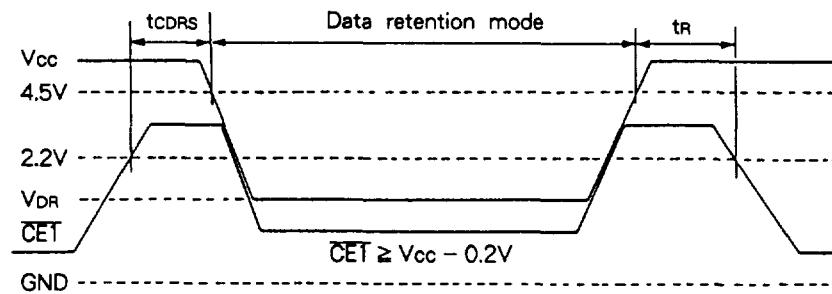
Item	Symbol	Test conditions	-70LL/10LL			Unit
			Min.	Typ.	Max.	
Data retention voltage	V _{DR}	* 1	2.0	—	5.5	V
Data retention current	I _{CCDR1}	* 1 V _{CC} =3.0V	—	0.1	2.5	μA
		Ta=0 to 70 °C	—	—	0.5	
	I _{CCDR2}	V _{CC} =2.0 to 5.5V * 1	—	0.2	6	μA
Data retention setup time	t _{CDRS}	Chip disable to data retention mode	0	—	—	ns
Recovery time	t _R		t _{RC} * 2	—	—	ns

* 1. $\overline{CE1} \geq V_{CC}-0.2V$, $CE2 \geq V_{CC}-0.2V$ [$\overline{CE1}$ Control] or $CE2 \leq 0.2V$ [CE2 Control]

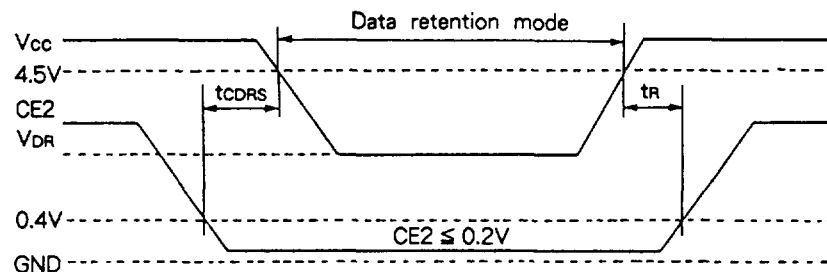
* 2. t_{RC}: Read cycle time

Data Retention Waveform

1. $\overline{CE1}$ control



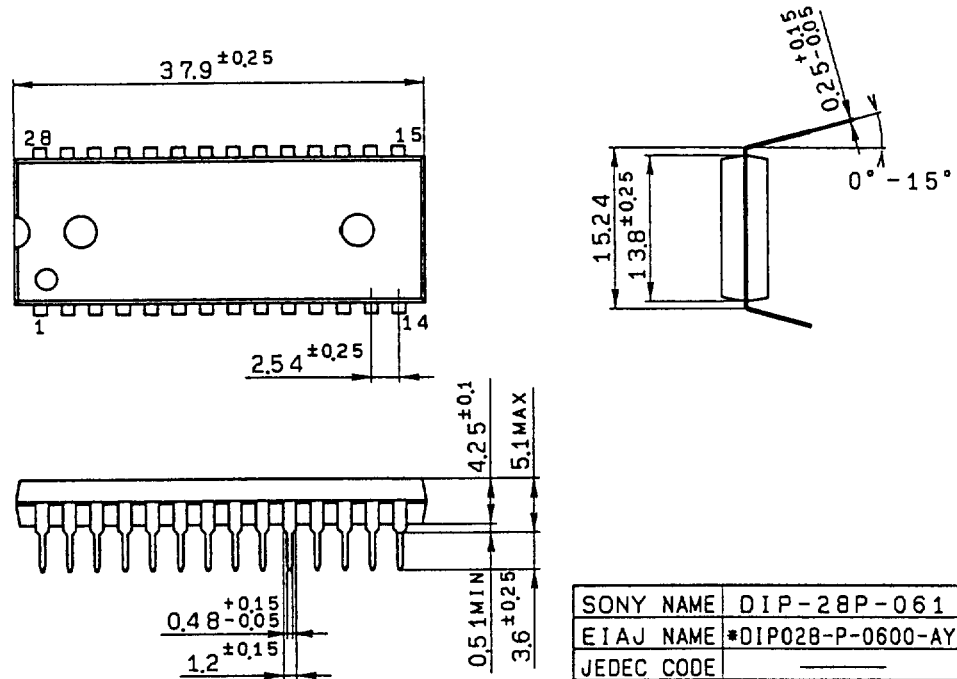
2. CE2 control



Package Outline Unit : mm

CXK5864CP

28pin DIP (Plastic) 600mil



CXK5864CM

28pin SOP (Plastic) 450mil 0.7g

